EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L7	650	semiconductor and ((base or frame or substrate) same ((groove or recess or cavity) with adhesion)) and (@ad<"20040129" or @rlad<"20040129")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/23 15:50
L8	1628	semiconductor and ((encapsul$6 or resin) same (((base or frame or substrate) with (metal or copper or cu or Al or aluminum or conductive)) with (groove or wing or cavity or recess$3))) and (@ad<"20040129" or @rlad<"20040129")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/23 16:07
L9	31	semiconductor and ((encapsul$6 or resin) same (((base or frame or substrate) with (metal or copper or cu or Al or aluminum or conductive)) with (groove or wing or cavity or recess$3))) and (@ad<"20040129" or @rlad<"20040129") and ((transparent or translucent) with (encapsul$6 or regin))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/23 16:08
L10	998	(257/432-434).ccls. and ((base or frame or substrate) with (metal or copper or cu or Al or aluminum or conductive)) and (@ad<"20040129" or @rlad<"20040129")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/23 16:16
L11	110	(257/678 or 257/680).ccls. and ((base or frame or substrate) with (metal or copper or cu or Al or aluminum or conductive)) and ((encapsul$5 or resin) with (transparent or translucent)) and (@ad<"20040129" or @rlad<"20040129")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/23 16:19
L12	348	(257/796).ccls. and ((base or frame or substrate) with (metal or copper or cu or Al or aluminum or conductive)) and (encapsul$5 or resin) and (@ad<"20040129" or @rlad<"20040129")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/23 16:21